ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES*	l Composition De ht 2005. IPC, Bannock al and Pan-American c	<b>claration</b> burn, Illinois. A opyright conver	Il rights reserved un ntions.	nder both	This docume level parts, t	ent is a declarati he declaration e	on of the subst ncompasses al	ances wi l lower le	thin the manufacture evel materials for w	rer listed ite hich the m	em. Note: i anufacturer	f the item is an as r has engineering	sembly with low responsibility.	
	1 IPC Web Site for Information on IPC-1752 Standard			Form Type Distribute	Form Type * Declaration Class *				omogeneous Materi	terials and Mfg Information				
upplier Information														
ompany name*	Company unique ID			1	Unique ID Authority				Response Date*					
nsemi									2024-05-19					
ontact Name	Title - Contact			]	Phone - Contact*				Email - Contact*					
Product-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com					
uthorized Representative*	Title - Repres	Title - Representative			Phone - Representative*				Email - Representative*					
roduct-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
Requester Item Number	er Mfr Iter	n Number	Number Mfr Item Name			Effective Date	Date Version Manufacturing Site		nufacturing Site	v	Veight*	UOM	Unit Type	
	NOIP15	NOIP1SE0480A-STI1 P		PYTHON480 1/3.6", RGB_ CRA1.65		2024-05-19		TW	TWU		8.3603	mg	Each	
Ianufacturing Proccess In	nformation								-			·		
Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 M		-STD-020 MSL	. Rating	Peak Process Body Tempera		perature	Max Time at Peak	Temperatu	ire Numb	per of Reflow Cyc	les	
SnAgCu		CU Alloy 4		l .		245	C		30		ls 3			
omments														
or more information regarding	material composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of					
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted						
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all					
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the					
Supplier Digital Signature Ra	stislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.6894	mg	Supplier	Silicon (Si)	7440-21-3		6.6894	mg
Glass Attach Epoxy	0.0053	mg		Miscellaneous	trade secret		0.0007	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		0.0046	mg
Glass Lid /Cap	29.3747	mg	Supplier	Boron Trioxide (B2O3)	1303-86-2		2.9375	mg
			Supplier	Magnesium Monoxide (MgO)	1309-48-4		1.4687	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		1.4687	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.9375	mg
			Supplier	Calcium Monoxide (CaO)	1305-78-8		1.4687	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		19.0936	mg
Metal Shielding	0.0483	mg	Supplier	Copper (Cu)	7440-50-8		0.0002	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0481	mg
RDL	0.053	mg	В	Nickel (Ni)	7440-02-0		0.0328	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.0001	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0198	mg
Solder Ball	2.1563	mg	Supplier	Silver (Ag)	7440-22-4		0.0647	mg
			Supplier	Tin (Sn)	7440-31-5		2.0808	mg
			Supplier	Copper (Cu)	7440-50-8		0.0108	mg
Substrate and Solder Mask	0.0333	mg	Supplier	Epoxy Phenol Novolak Resin	28064-14-4		0.0033	mg
			Supplier	9-Phenylacridine	602-56-2		0.0017	mg
			Supplier	2-Propenoic acid	1245638-61-2		0.0033	mg
			Supplier	3-Methoxy-1-butanol	2517-43-3		0.0083	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.0083	mg
			Supplier	1-Methoxy-2-propyl acetate (MPA)	108-65-6		0.0083	mg